

ABSTRACT OF THE DISCLOSURE

An integrated circuit package housing an electronic imager die for use in a conventional SLR camera is disclosed. The package includes a substrate with conductive circuitry and an electronic imager die with a surface area approximately the size of a camera focal image plane mounted thereon. A frame with an inwardly depending lip and integral channel is bonded to the substrate and is provided with a transparent window, the window and frame residing at the focal image plane. The window and frame protect the active die surface from contamination. The channel volume is used for wirebond interconnects from the inactive perimeter of the imager die to the substrate circuitry. Additionally, the substrate contains additional area for supporting electronics or optional circuitry, all of which reside at the film rails and along the film path. In this manner, an electronic film package for use in a conventional camera is provided that allows the use of an imager die area of up to the size of the camera's focal image plane.